

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L15	2	(29/610.1).ccls. and (thick adj resistor) and substrate and (passivation or mask or photomask or (dry adj film) or dielectric)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/28 08:06
L30	27	(29/825,829,846).ccls. and (resistor) and (circuit) and substrate and (passivation or mask or photomask or (dry adj film)) and titanium and copper and (electroplat\$3 or plat\$3) and (board)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/28 08:12
L31	4	(29/825,829,846).ccls. and (resistor) and (circuit) and substrate and ((passivation or mask or photomask or (dry adj film) or protection) adj layer) and titanium and copper and (electroplat\$3 or plat\$3) and (board)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/28 08:11
L32	1	(29/857,868,874).ccls. and (resistor) and (circuit) and substrate and ((passivation or mask or photomask or (dry adj film) or protection) adj layer) and titanium and copper and (electroplat\$3 or plat\$3) and (board)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/28 08:13
L34	3	(361/321.4).ccls. and (resistor) and (circuit) and substrate and (passivation or mask or photomask or (dry adj film)) and (electroplat\$3 or plat\$3) and (board)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/28 08:11
L35	5	(216/16,40).ccls. and (resistor) and (circuit) and substrate and (passivation or mask or photomask or (dry adj film)) and titanium and copper and (electroplat\$3 or plat\$3) and (board)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/28 08:13
L36	35	(174/255,260).ccls. and (resistor) and (circuit) and substrate and (passivation or mask or photomask or (dry adj film)) and titanium and copper and (electroplat\$3 or plat\$3) and (board)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/28 08:14

L37	15	(174/255,260).ccls. and (resistor) and (circuit) and substrate and ((passivation or mask or photomask or (dry adj film) or protection) adj layer) and titanium and copper and (electroplat\$3 or plat\$3) and (board)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/28 08:15
L39	1	(438/745).ccls. and (resistor) and (circuit) and substrate and (passivation or mask or photomask or (dry adj film)) and titanium and copper and (electroplat\$3 or plat\$3) and (board)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/28 08:14
L40	2	(427/101).ccls. and (resistor) and (circuit) and substrate and ((passivation or mask or photomask or (dry adj film) or protection) adj layer) and titanium and copper and (electroplat\$3 or plat\$3) and (board)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/28 08:15
S1	6	(ru-shao-pin).in.	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/25 13:56
S2	0	("thickadjfilmadjresistor").PN.	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2005/10/25 13:56
S3	1518	thick adj film adj resistor	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/25 13:57
S4	17	(thick adj film adj resistor) and (thin adj film adj circuit)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/25 14:00
S5	1332	(thick adj film adj resistor) and (circuit)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/25 14:00
S6	249	(thick adj film adj resistor) and (circuit) and substrate and (passivation or mask or photomask)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/25 14:01
S7	260	(thick adj film adj resistor) and (circuit) and substrate and (passivation or mask or photomask or (dry adj film))	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/25 14:01
S8	66	(thick adj film adj resistor) and (circuit) and substrate and (passivation or mask or photomask or (dry adj film)) and titanium	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/25 14:02

S9	63	(thick adj film adj resistor) and (circuit) and substrate and (passivation or mask or photomask or (dry adj film)) and titanium and copper	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/25 14:02
S10	52	(thick adj film adj resistor) and (circuit) and substrate and (passivation or mask or photomask or (dry adj film)) and titanium and copper and expos\$3	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/25 14:02
S11	40	(thick adj film adj resistor) and (circuit) and substrate and (passivation or mask or photomask or (dry adj film)) and titanium and copper and expos\$3 and (electroplat\$3 or plat\$3)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/25 14:03
S12	22	(thick adj film adj resistor) and (circuit) and substrate and (passivation or mask or photomask or (dry adj film)) and titanium and copper and expos\$3 and (electroplat\$3 or plat\$3) and (board)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/28 08:02
S13	1	("6507993").PN.	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2005/10/26 13:14
S14	23	(thick adj resistor) and circuit and electrode and substrate	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/26 13:20
S15	25	(thick adj resistor) and electrode and substrate	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/26 13:21
S16	314956	(thick adj resistor) and electrode and substrate (passivation or mask or photomask)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/26 13:21
S17	9	(thick adj resistor) and electrode and substrate and (passivation or mask or photomask)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/26 13:22
S18	9	(thick adj resistor) and electrode and substrate and (passivation or mask or photomask or (dry adj film))	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/26 13:22
S19	4	(thick adj resistor) and electrode and substrate and (passivation or mask or photomask or (dry adj film)) and (plat\$3 or electroplat\$3)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/26 13:26
S20	7	("5379016").URPN.	USPAT	OR	ON	2005/10/26 13:26

S21	2	(thick adj resistor) and board and (circuit or wiring) and substrate and (passivation or mask or photomask or (dry adj film)) and (plat\$3 or electroplat\$3)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/26 13:28
S22	1	(thick adj resistor) and (printed adj (circuit or wiring) adj board) and (passivation or mask or photomask or (dry adj film)) and (plat\$3 or electroplat\$3)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/26 13:43
S23	2	((("4892776") or ("5510594"))).PN.	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2005/10/26 13:31
S24	29	("4892776").URPN.	USPAT	OR	ON	2005/10/26 13:31
S25	18	("2945180" "3808576" "3813631" "4174513" "4737747" "4888574" "4892776" "5336391" "5422313" "5483217" "5756971" "5864281" "5907273" "5994997" "6141870" "6232042" "6248612").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/26 13:34
S26	11	("5994997").URPN.	USPAT	OR	ON	2005/10/26 13:36
S27	5	("4293839").URPN.	USPAT	OR	ON	2005/10/26 13:40
S28	5	("4293839").URPN.	USPAT	OR	ON	2005/10/26 13:41
S29	2	(thick adj resistor) and (board) and (passivation or mask or photomask or (dry adj film)) and (plat\$3 or electroplat\$3)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/26 13:42
S30	3318	(resistor) and (printed adj (circuit or wiring) adj board) and (passivation or mask or photomask or (dry adj film)) and (plat\$3 or electroplat\$3)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/26 13:43
S31	93	((embedd\$3 or integrat\$3) near resistor) and (printed adj (circuit or wiring) adj board) and (passivation or mask or photomask or (dry adj film)) and (plat\$3 or electroplat\$3)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/26 13:43
S32	28	((embedd\$3 or integrat\$3) near resistor) same (printed adj (circuit or wiring) adj board) and (passivation or mask or photomask or (dry adj film)) and (plat\$3 or electroplat\$3)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/26 13:43
S33	15	(takata-eiichi).in.	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/26 14:00

S34	31	(alpha adj tungsten) and tungsten	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/26 14:01
S35	11	("5994997").URPN.	USPAT	OR	ON	2005/10/27 07:06
S36	1419	((titanium near copper) with (layer or film or coating))	USPAT	OR	ON	2005/10/27 07:07
S37	184	((titanium near copper) near (layer or film or coating))	USPAT	OR	ON	2005/10/27 07:07
S38	4	((((titanium near copper) near (layer or film or coating)) with (terminal or electrode)) and (resistor or resistive or resistance))	USPAT	OR	ON	2005/10/27 07:08
S39	26711	(motor or stator or rotor) and winding and slot	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/27 08:05
S40	7240	(motor or stator or rotor) and (winding with slot)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/27 08:05
S41	2427	(motor or stator or rotor) and (winding with slot) and stack\$3	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/27 08:06
S42	1228	(motor or stator or rotor) and ((winding with slot) same stack\$3)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/27 08:06
S43	1228	(motor or stator or rotor) and ((winding with slot) same (stack or stacked or stacking))	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/27 08:07
S44	695	(motor or stator or rotor) and ((winding with slot) with (stack or stacked or stacking))	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/27 08:07
S45	673	(motor or rotor) and ((winding with slot) with (stack or stacked or stacking))	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/27 08:07
S46	570	(rotor) and ((winding with slot) with (stack or stacked or stacking))	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/27 08:08
S47	303	(rotor) same ((winding with slot) with (stack or stacked or stacking))	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/27 08:08
S48	220	(rotor) same ((winding with slot) with (stack or stacked or stacking)) and turn\$3	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/27 08:08
S49	220	(rotor) same ((winding with slot) with (stack or stacked or stacking)) and (turn or turned or turning)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/27 08:09

S50	44	(rotor) same ((winding with slot) with (stack or stacked or stacking) with (turn or turned or turning))	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/27 12:18
S51	8	("1799021" "2085099" "2333575" "5886434" "5986380").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/27 08:11
S52	13	("5986380").URPN.	USPAT	OR	ON	2005/10/27 08:24
S53	1	("5162144").PN.	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2005/10/27 12:23
S54	0	("(copperadjflash)withsputter\$3").PN.	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2005/10/27 12:24
S55	4	(copper adj flash) with sputter\$3	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/27 12:49
S56	6373	resistor and electrode and (dielectric or passivation) with (thick or thickness)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/27 12:51
S57	2115	resistor and electrode and (dielectric or passivation) near (thick or thickness)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/27 12:51
S58	199	resistor and electrode and (dielectric or passivation) near (thick or thickness) and electrode near (thick or thickness)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/27 12:53
S60	119	resistor and electrode and (dielectric or passivation) near (thick or thickness) and electrode near (thick or thickness) and micro\$5	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/27 12:58
S61	106	resistor and electrode and (dielectric or passivation) near (thick or thickness) and electrode near (thick or thickness) and (micro or micron or micrometer)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/27 13:00
S62	106	resistor and (dielectric or passivation) near (thick or thickness) and electrode near (thick or thickness) and (micro or micron or micrometer)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/27 13:03
S63	91	resistor and (dielectric or passivation) near (thick or thickness) and electrode near (thick or thickness) and (micron or micrometer)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/27 13:03